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(54) **Title:** COMPOSITIONAL OPTICAL EMISSION SPECTROSCOPY FOR DETECTION OF PARTICLE INDUCED ARCS IN
A FABRICATION PROCESS

(57) **Abstract:** Described herein are architectures, platforms and methods
for detecting and analyzing anomalous events (i.e., arcing events) from
spectral data gathered during a wafer fabrication process.

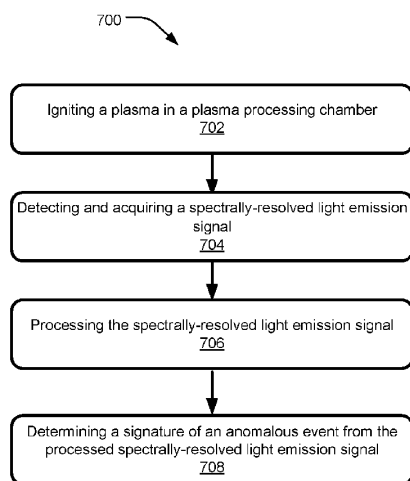


FIG. 7

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